

ASSIGNMENT

09-20-2004  
102839826

ET

9-10-04

22278 U.S. PTO  
10/939082  
091004

Commissioner of Patents:

Please record the attached document.

- 1. Name of conveying party:
  - a) Maurice O. Othieno
  - b) Hong T. Lim
  - c) Qwai H. Low
- 2. Name and address of receiving party:
  - a) Name: LSI Logic Corporation
  - Address: 1621 Barber Lane  
Milpitas, CA 95035

- 3. Nature of conveyance:
 

|  |  |
|--|--|
| <input checked="" type="checkbox"/> Assignment | <input type="checkbox"/> Merger            |
| <input type="checkbox"/> Security Agreement    | <input type="checkbox"/> Change of Name    |
| <input type="checkbox"/> Other _____           | <input type="checkbox"/> License Agreement |

Execution Date: September 9, 2004

- 4. Application Number or Patent Number: Filed Herewith

The title of the application is: **INTEGRATED HEATSPREADER FOR USE IN WIRE BONDED BALL GRID ARRAY SEMICONDUCTOR PACKAGES**

- 5. Please send all correspondence concerning this document to:

**LSI Logic Corporation  
1621 Barber Lane  
Milpitas, CA 95035**

**Customer Number: 24319**

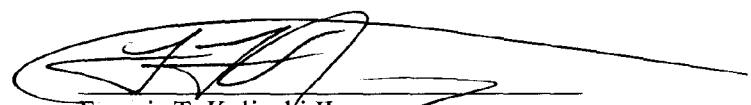
- 6. Total number of applications and patents involved: 1

- 7. Total fee (37 CFR 3.41): \$40.00

- Enclosed.
- Charge to Deposit Account No. 12-2252 (Order No. 04-0022).
- Any additional fees are authorized to be charged to Deposit Account No. 12-2252 (Order No. 04-0022).

Date: September 9, 2004

09/17/2004 GTON11 00000070 122252 10939082  
01 FC:8021 40.00 DA

  
Francis T. Kalinski II  
Registration No. 44,177

Total number of pages including this cover sheet, attachments and documents: 02

Attorney Docket No. 04-0022/LSI1P253

(Revised 9/03)

**PATENT  
REEL: 015786 FRAME: 0125**

**ASSIGNMENT**

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the undersigned, Maurice O. Othieno, Hong T. Lim, and Qwai H. Low, do hereby sell, assign, and transfer to: LSI LOGIC CORPORATION, a corporation of Delaware, having a place of business at 1621 Barber Lane, Milpitas, California 95035, ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent,

- ( X ) which has been executed by the undersigned concurrently herewith,
- ( ) which was filed on \_\_\_\_\_, 20\_\_\_\_ and assigned Application No. \_\_\_\_\_,

and is entitled: **INTEGRATED HEATSPREADER FOR USE IN WIRE BONDED BALL GRID ARRAY SEMICONDUCTOR PACKAGES**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Name: Maurice Othieno Date: 9/9/2004, 2004 Witness: [Signature]  
 Maurice O. OTHIENO

Name: Hong T. Lim Date: 9/9/04, 2004 Witness: [Signature]  
 Hong T. LIM

Name: Qwai H. Low Date: 9/9/04, 2004 Witness: [Signature]  
 Qwai H. LOW

04-0022/LSI1P253  
Assignment  
(Revised 011995)